Pin Pre-amplifier with AGC for 3.3V Fiber Optic Applications to 622 Mbps

The MC2009 is a low-noise, transimpedance amplifier with AGC, manufactured in low-cost CMOS. Its wide dynamic range, differential output and high PIN bias make it well suited for telecommunications, especially OC-12/STM-4. However, the MC2009 is intended to meet the needs of both Telecom and Datacom users.

The MC2009 is available in die form. For optimum system performance die should be mounted in close proximity with the photodetector.

The MC2009 is designed to be used with the Mindspeed MC2044C Postamplifier IC. When combined with a photodiode, the chip set forms a high performance, low cost 3.3V receiver.

Applications
- ATM/SDH/SONET
- PON/FTTH

Features
- Low cost IC fabricated in CMOS.
- Receiver sensitivity better than -32 dBm @ 622 Mbps.
- Minimum 340 MHz bandwidth and multi-pole roll off allows a wide range of operation up to 622 Mbps.
- Typical differential transimpedance at low signal levels of 40Ω.
- AGC gives continuous operation to +3 dBm
- > 33 dB power-supply noise rejection.
- Typical 130 mW power consumption at 3.3V supply.
- Monitor output gives linear indication of received optical power.
- Differential output.

Functional Block Diagram
Ordering Information

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Package</th>
<th>Operating Temperature</th>
</tr>
</thead>
<tbody>
<tr>
<td>MC2009-XX*</td>
<td>Waffle Pack</td>
<td>−40 °C to 85 °C</td>
</tr>
<tr>
<td>MC2009-XX*</td>
<td>Expanded whole wafer on a ring</td>
<td>−40 °C to 85 °C</td>
</tr>
</tbody>
</table>

* Consult price list for exact part number when ordering.

Revision History

<table>
<thead>
<tr>
<th>Revision</th>
<th>Level</th>
<th>Date</th>
<th>ASIC Revision</th>
</tr>
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<tbody>
<tr>
<td>D</td>
<td>Preliminary</td>
<td>July 2004</td>
<td>Updated Block Diagram and Top Level Diagram&lt;br&gt;Updated Absolute Maximum Ratings&lt;br&gt;Updated AC Characteristics</td>
</tr>
</tbody>
</table>
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1.0 Functional Description

1.1 Overview

The MC2009 is a low-noise, transimpedance amplifier with AGC, manufactured in low-cost CMOS. Its wide dynamic range, differential output and high PIN bias make it well suited for telecommunications, especially OC-12/STM-4. However, the MC2009 is intended to meet the needs of both Telecom and Datacom users.

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Figure 1-1. M02009 Block Diagram
1.2 Features

- Low cost IC fabricated in CMOS.
- Receiver sensitivity better than -32 dBm @ 622 Mbps.
- Minimum 340 MHz bandwidth and multi-pole roll off allows a wide range of operation up to 622 Mbps.
- Typical differential transimpedance at low signal levels of 40Ω.
- AGC gives continuous operation to +3 dBm
- > 33 dB power-supply noise rejection.
- Typical 130 mW power consumption at 3.3V supply.
- Monitor output gives linear indication of received optical power.
- Differential output.

1.3 General Description

1.3.1 TIA (Transimpedance Amplifier)

The transimpedance amplifier consists of a high gain single-ended CMOS amplifier, with a feedback resistor. The feedback creates a virtual low impedance at the input and virtually all of the input current passes through the feedback resistor, defining the voltage at the output. Advanced CMOS design techniques are employed to maintain the stability of these stages across all input conditions.
Single-ended amplifiers have inherently poor power supply noise rejection. For this reason, an on-chip low dropout linear regulator has been incorporated into the design to give excellent noise rejection up to several MHz. Higher frequency power supply noise is removed by external decoupling.

The circuit is designed for PIN photodiodes in the “grounded cathode” configuration, with the anode connected to the input of the TIA and the cathode connected to AC ground. Reverse DC bias is applied to reduce the photodiode capacitance.

1.3.2 AGC
The MC2009 has been designed to operate over the input range of +3 dBm to –32 dBm at long wavelengths. This represents a ratio of 1:3000, whereas the acceptable dynamic range of the output is only 1:100 which implies a compression of 30:1 in the transimpedance. The design uses a MOS transistor to achieve the transimpedance variation.

Another feature of the AGC is that it is only operates on signals greater than –20 dBm (© 0.9A/W). This knee in the gain response is important when setting “signal detect” functions in the following postamplifier. It also aids in active photodiode alignment.

The AGC pad allows the AGC to be disabled during photodiode alignment by grounding the pad through a low impedance. The AGC control voltage can be monitored during normal operation at this pad by a high impedance (>10 MΩ) circuit. In addition, taking this pad to VCC +1.2V enables an internal test oscillator which supplies a 1 MHz 10 uA pk(approximate) square wave current internally between the PIN K and PIN A pads to emulate a photodiode for test purposes.

1.3.3 Output Stage
The signal from the TIA enters a phase splitter and a pair of voltage follower outputs. These are designed to drive a high impedance (>500Ω) load. They are stable for driving capacitive loads such as interstage filters. Each output has its own GND pad, all four GND pads on the chip should be connected for proper operation.

Since the MC2009 exhibits rapid rolloff, external filtering is not required.

1.3.4 Monitor Output
High impedance output sinks a 1:1 replica of average photodiode current for monitoring purposes.

Note that this output is provided because in this device it is not possible to connect the photodiode cathode to Vcc. For the correct operation of the AGC and DC restore, the photodiode cathode must be connected to the PINK pin. The MC2009 measures the photodiode current and uses this information to set the transimpedance and reduce the DCoffset of the outputs. To convert this output to a voltage, a resistor to Vcc should be used. Note that for linearity, ensure that Vmon is always > 1V.
Figure 1-3. Typical Performance (1 of 3)

Typical Bandwidth vs. Photodiode Capacitance

Sensitivity vs Responsivity vs Photodiode Capacitance
Figure 1-4. Typical Performance (2 of 3)

Monitor Ratio

Input Current v Average MONITOR Current @Vcc=3.3V

Supply Voltage v Average Supply Current
Figure 1-5.  Typical Performance (3 of 3)

**Input Current vs Dout Average Transimpedance**

![Graph showing input current vs average transimpedance at 21°C](image)

- **Transimpedance (Ohms)**
- **Input Current (μA pk-pk)**

**PINK Input Current vs Average PINK Voltage**

![Graph showing PINK input current vs average PINK voltage at 3.3V](image)

- **Average PINK Voltage (V)**
- **PINK Input Current (mA)**

**Eye Diagram @ -20 dBm**

![Eye Diagram Image](image)
1.3.5 Assembly

The M02009 is designed to work with a wirebond inductance of 1 nh +/- 0.25 nh. Many existing TO-Can configurations will not allow wirebond lengths that short, since the PIN diode submount and the TIA die are more than 1 mm away in the vertical direction, due to the need to have the PIN diode in the correct focal plane. This can be remedied by raising up the TIA die with a conductive metal shim. This will effectively reduce the bond wire length. Refer to Figure 5 on the following page for details. Mindspeed recommends ball bonding with a 1 mil (25µm) gold wire.

In addition, please refer to the Mindspeed Product Bulletin (document number 0201X-PBD-001). Care must be taken when selecting chip capacitors, since they must have good low ESR characteristics up to 1 Ghz. It is also important that the termination materials of the capacitor be compatible with the attach method used.

Tin/Lead (Pb/Sn) or Tin (Sn) solder finish capacitors are incompatible with silver-filled epoxies. Palladium/Silver (Pd/Ag) terminations are compatible with silver filled epoxies. Solder can be used only if the substrate thick-film inks are compatible with Tin-bearing solders.
Figure 1-6. TO-Can Assembly Diagram

NOT Recommended Example
- PIN Diode
- Capacitor
- Wire Bond
- TO Can Leads (x 4 or 5)
- TO-CAN Header

Recommended Example
- PIN Diode
- Capacitor
- Wire Bond
- TO Can Leads (x 4 or 5)
- TO-CAN Header
1.4 Applications

- ATM/SDH/SONET
- PON/FTTH

1.5 Pin Definitions

<table>
<thead>
<tr>
<th>Name</th>
<th>Function</th>
</tr>
</thead>
<tbody>
<tr>
<td>GND</td>
<td>Ground. Connect to the most negative supply. All pads should be connected</td>
</tr>
<tr>
<td>DOUT</td>
<td>Non-Inverted Data Output. Differential output with DOUT</td>
</tr>
<tr>
<td>VCC</td>
<td>Power. Connect to most positive supply. Either or both pads may be used.</td>
</tr>
<tr>
<td>PINK</td>
<td>Photodiode Cathode connection. Connect photodiode between PINK and PINA.</td>
</tr>
<tr>
<td></td>
<td>Connect de-coupling cap between PINK and GND (470pF typ).</td>
</tr>
<tr>
<td>PINA</td>
<td>Photodiode Anode connection. Connect photodiode between PINA and PINK.</td>
</tr>
<tr>
<td>DOUT</td>
<td>Inverted Data Output. Differential output with DOUT</td>
</tr>
<tr>
<td>MON</td>
<td>Optical input power monitor. Current sink output, current flow into pin.</td>
</tr>
<tr>
<td>AGC</td>
<td>AGC disable/monitor (test mode enable)</td>
</tr>
</tbody>
</table>
## 2.1 Absolute Maximum Ratings

### Table 2-1. Absolute Maximum Ratings

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Rating</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>VCC</td>
<td>Power supply (VCC-GND)</td>
<td>4.5 V</td>
<td></td>
</tr>
<tr>
<td>TA</td>
<td>Operating ambient</td>
<td>-40 to +85 °C</td>
<td></td>
</tr>
<tr>
<td>TJ</td>
<td>Junction temperature (die)</td>
<td>+150 °C</td>
<td></td>
</tr>
<tr>
<td>TSTG</td>
<td>Storage temperature</td>
<td>-65 to +150 °C</td>
<td></td>
</tr>
<tr>
<td>IMAX</td>
<td>Input Overload Current</td>
<td>4.5 MApp</td>
<td></td>
</tr>
</tbody>
</table>

## 2.2 Recommended Operating Conditions

### Table 2-2. Recommended Operating System

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Rating</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>VCC</td>
<td>Power supply (VCC-GND)</td>
<td>3.3 ± 10% V</td>
<td></td>
</tr>
<tr>
<td>TJ</td>
<td>Junction temperature (die)</td>
<td>-40 to +100 °C</td>
<td></td>
</tr>
<tr>
<td>TA</td>
<td>Operating ambient temperature</td>
<td>-40 to +85 °C</td>
<td></td>
</tr>
</tbody>
</table>

## 2.3 DC Characteristics

### Table 2-3. DC Characteristics

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Min.</th>
<th>Typ.</th>
<th>Max.</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>VB</td>
<td>PIN Photodiode bias voltage (PINK - PINA)</td>
<td>1.5</td>
<td>1.6</td>
<td>1.8</td>
<td>V</td>
</tr>
<tr>
<td>Voh &amp; VOL</td>
<td>Output High and Low Voltages</td>
<td>1.1</td>
<td>1.6</td>
<td>2.4</td>
<td>V</td>
</tr>
<tr>
<td>VCM</td>
<td>Common mode output voltage</td>
<td>1.4</td>
<td>1.6</td>
<td>1.9</td>
<td>V</td>
</tr>
<tr>
<td>ICC</td>
<td>Supply current (no loads)</td>
<td>--</td>
<td>30</td>
<td>45</td>
<td>mA</td>
</tr>
</tbody>
</table>

**NOTE:**
1. Die are tested and guaranteed at 25 °C, and are designed and characterized to operate over the whole temperature range.
# 2.4 AC Characteristics

## Table 2-4. AC Characteristics

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Min.</th>
<th>Typ.</th>
<th>Max.</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>R\textsubscript{OUT}</td>
<td>Output impedance (single ended)</td>
<td>30</td>
<td>45</td>
<td>60</td>
<td>Ω</td>
</tr>
<tr>
<td>I\textsubscript{INoise}</td>
<td>Total integrated input referred RMS noise</td>
<td>50</td>
<td>70</td>
<td>91</td>
<td>nA</td>
</tr>
<tr>
<td>G</td>
<td>Small signal Transimpedance</td>
<td>14</td>
<td>18</td>
<td>23</td>
<td>KΩ</td>
</tr>
<tr>
<td></td>
<td>Single ended</td>
<td>28</td>
<td>36</td>
<td>46</td>
<td></td>
</tr>
<tr>
<td></td>
<td>Differential</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>BW</td>
<td>Bandwidth (-3dB point optical)</td>
<td>340</td>
<td>400</td>
<td>460</td>
<td>MHz</td>
</tr>
<tr>
<td>PSSR</td>
<td>Power Supply Rejection Ratio (&lt;4 MHz)</td>
<td>27</td>
<td>30</td>
<td>31</td>
<td>dB</td>
</tr>
<tr>
<td>V\textsubscript{D}</td>
<td>Differential output voltage</td>
<td>600</td>
<td>800</td>
<td>1000</td>
<td>mV</td>
</tr>
<tr>
<td>LF cutoff</td>
<td>Lower frequency cutoff (-3 dB corner)</td>
<td>-</td>
<td>40</td>
<td>50</td>
<td>KHz</td>
</tr>
<tr>
<td>OS\textsubscript{Pulse}</td>
<td>Pulse overshoot</td>
<td>-</td>
<td>13</td>
<td>20</td>
<td>%</td>
</tr>
<tr>
<td>TP\textsubscript{WDD}</td>
<td>Pulse width distortion</td>
<td>-</td>
<td>3</td>
<td>8</td>
<td>%</td>
</tr>
<tr>
<td>T\textsubscript{AGC}</td>
<td>AGC Time constant</td>
<td>-</td>
<td>32</td>
<td>1800</td>
<td>us</td>
</tr>
<tr>
<td>Jitter</td>
<td>Jitter</td>
<td>-</td>
<td>145</td>
<td>200</td>
<td>ps, p-p</td>
</tr>
<tr>
<td>PIN(mean), min</td>
<td>Optical Sensitivity</td>
<td>-</td>
<td>-32</td>
<td>-</td>
<td>dBm</td>
</tr>
<tr>
<td>I\textsubscript{max}</td>
<td>Input Overload Current</td>
<td>-</td>
<td>-</td>
<td>4.5</td>
<td>mA\textsubscript{pp}</td>
</tr>
</tbody>
</table>

**NOTES:**

1. Measured with input capacitance, C\textsubscript{IN} = 0.7 pF
2. Assuming a photodiode responsivity of 0.9 A/W, at an extinction ratio of 10 dB and BER of 10\textsuperscript{-10} BW=415 MHz
3. The MC2009 is designed to drive a load >500 Ω.
4. Measured at 1 MHz, 1 μA
5. Measured at -30 dBm
6. AGC time constant can be increased by adding a capacitor from AGC pad to ground
7. Worst case occurs at the AGC knee point. This corresponds to approximate optical power levels in the range of -20 dBm to -25 dBm.
8. Guaranteed by design and characterization.
9. Optical input >= -20 dBm.
10. Die are tested and guaranteed at 25 °C, however are characterized to operate over the whole temperature range.
11. For a 30 db input signal change.
### 2.5 Bare Die Layout and X Y Coordinates

**Table 2-5. Bare Die Layout Example**

<table>
<thead>
<tr>
<th>Pad</th>
<th>X</th>
<th>Y</th>
</tr>
</thead>
<tbody>
<tr>
<td>GND</td>
<td>-307</td>
<td>300</td>
</tr>
<tr>
<td>GND\textsubscript{OUT}</td>
<td>-307</td>
<td>150</td>
</tr>
<tr>
<td>D\textsubscript{OUT}</td>
<td>-307</td>
<td>0</td>
</tr>
<tr>
<td>MON</td>
<td>-307</td>
<td>-150</td>
</tr>
<tr>
<td>V\textsubscript{CC}</td>
<td>-307</td>
<td>-300</td>
</tr>
<tr>
<td>PINK</td>
<td>-99.25</td>
<td>-397</td>
</tr>
<tr>
<td>PINA</td>
<td>124.8</td>
<td>-397</td>
</tr>
<tr>
<td>V\textsubscript{CC}</td>
<td>307</td>
<td>-300</td>
</tr>
<tr>
<td>AGC</td>
<td>307</td>
<td>-150</td>
</tr>
<tr>
<td>D\textsubscript{OUT}</td>
<td>307</td>
<td>0</td>
</tr>
<tr>
<td>GND\textsubscript{OUT}</td>
<td>307</td>
<td>150</td>
</tr>
<tr>
<td>GND</td>
<td>307</td>
<td>300</td>
</tr>
</tbody>
</table>

**Notes:**
- Process technology: CMOS, Silicon Nitride passivation
- Die thickness: 300 µm
- Pad metallization: Aluminum
- Die size: 890 µm x 1020 µm
- Pad opening: 86 µmsq
- Octagonal pad: 70 µm across flat
- Pad Centers in µm referenced to center of device.
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